

DIAMOND'S UNFINISHED REVOLUTION

Preparing for the next 100 years

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OPENING PREMISE

Lab-grown diamond is still in its opening chapters

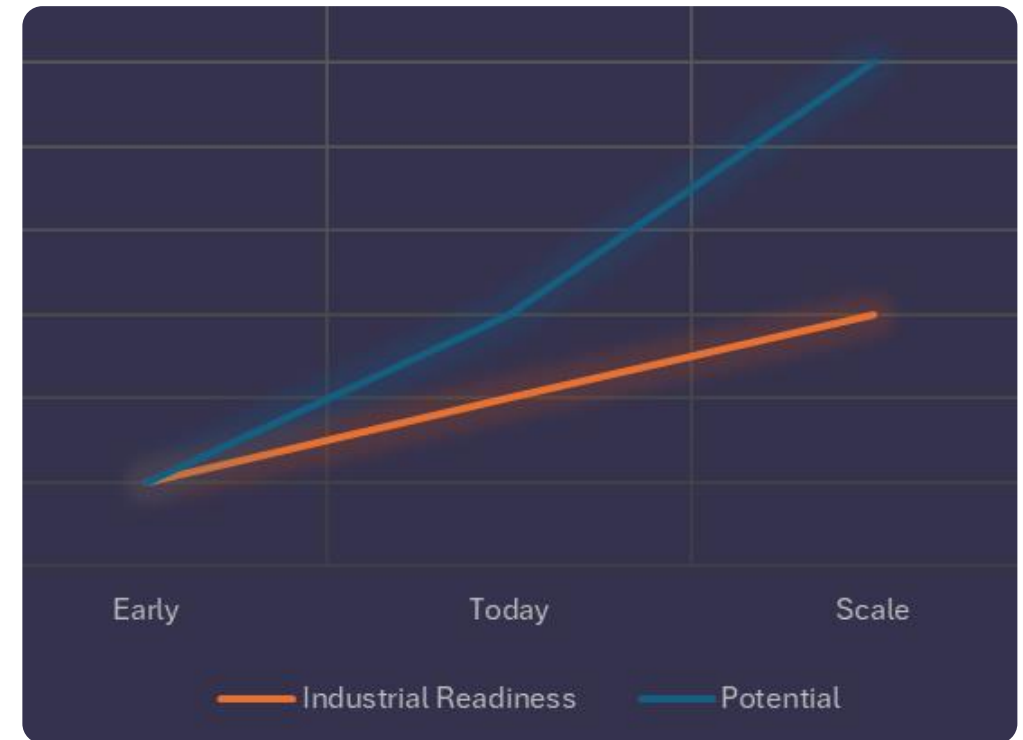
The first 70 years were about discovery and niche adoption.

The next century will be about greater scale, integration, and broader impact.

Diamond: “A 100 Year Material”

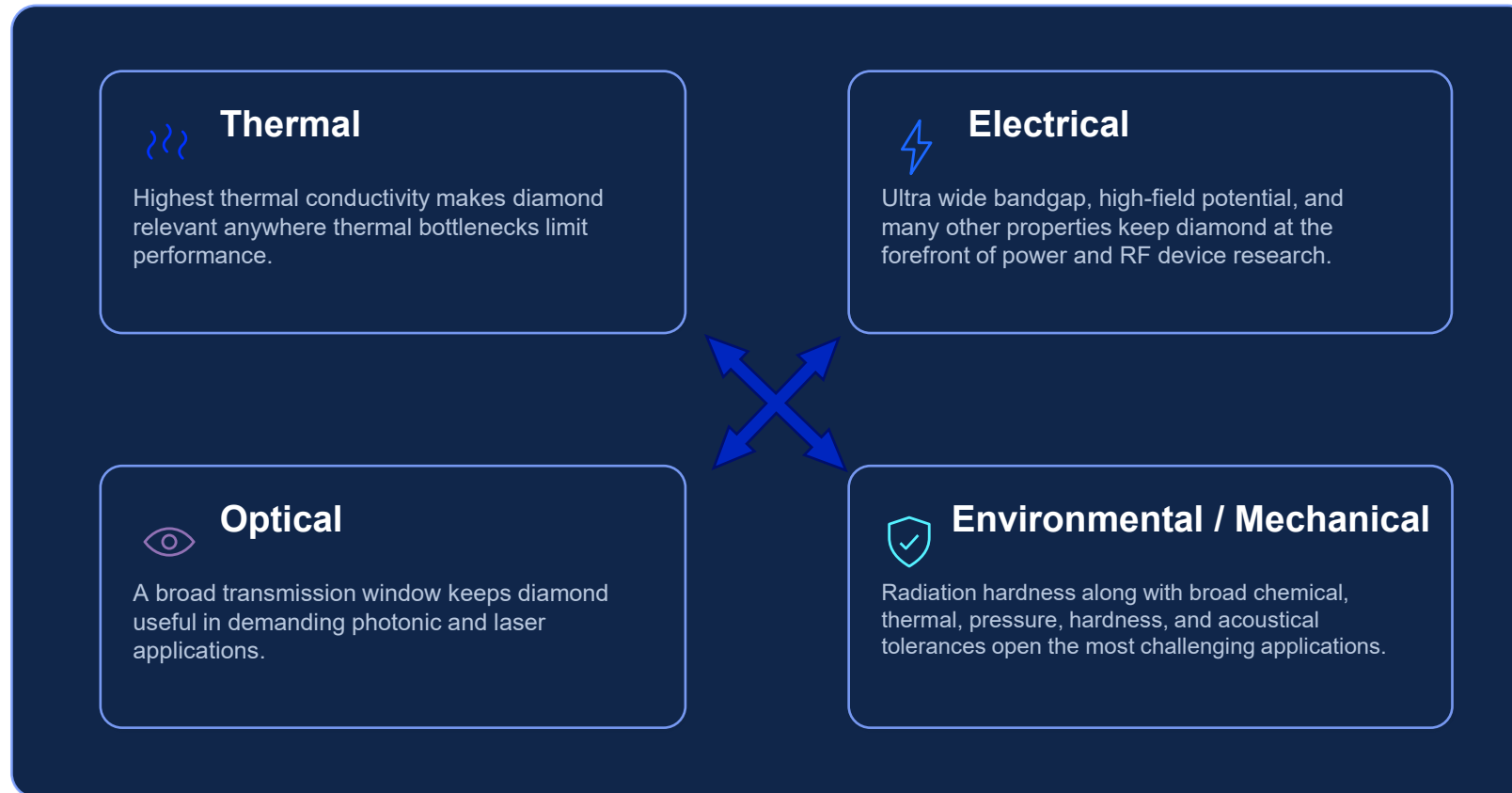
A phrase that captured diamond's promise - but not the pace of its adoption.

- 1 Lab-grown diamond has existed for decades, yet the field is still early relative to its potential.
- 2 Applications have been realized faster than the manufacturing capabilities to support them.
- 3 This mismatch continues to broaden - potential versus industrial readiness



Diamond's advantage is not any one property — it is the combination

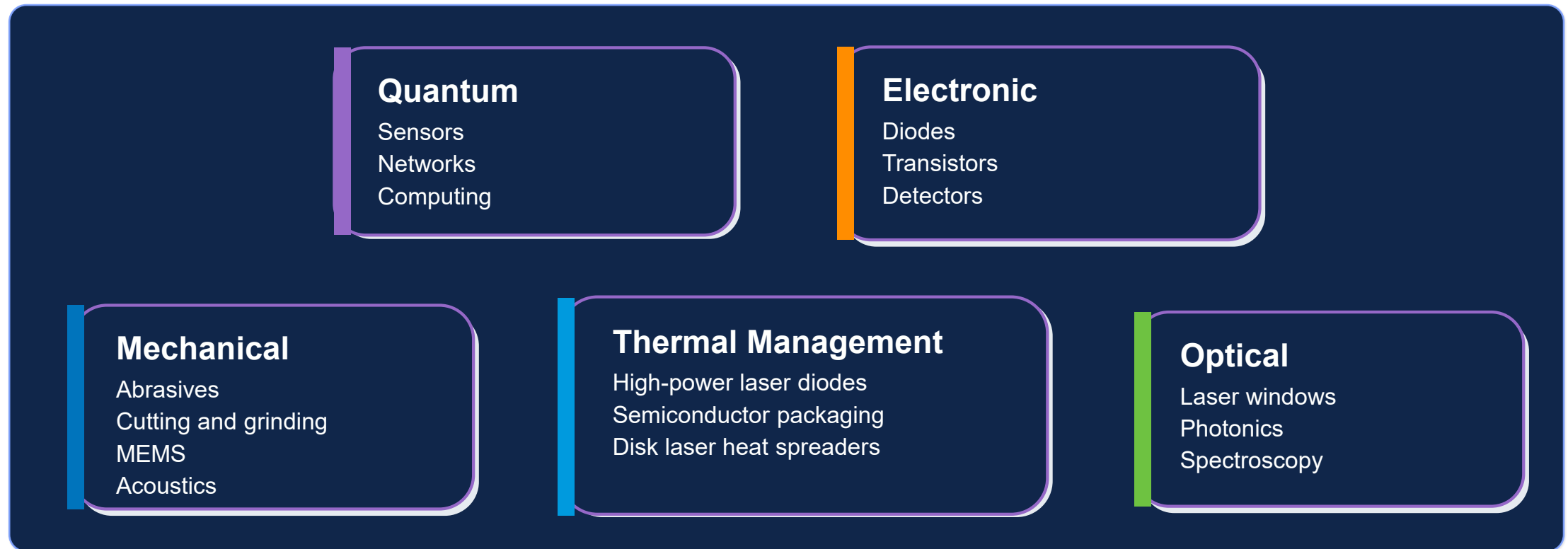
When thermal, electrical, optical, and environmental strengths align, new applications emerge.



Diamond's application space is broad — and still expanding

Although it is rarely the first material considered.

When other materials reach their limits, new diamond applications emerge.



EMERGENT APPLICATIONS

Many of diamond's most important applications were not predicted

Adoption has been shaped by emerging system bottlenecks.

The priority is not perfect forecasting — it is building the capability to respond.



EUV lithography

Optical properties, beam quality, and reliability requirements created demand few would have forecast early on.



AI thermal management

As compute density rises, demanding thermal management requirements create a new pull for high-conductivity materials.



Quantum sensing

Magnetometers and other color-center applications are expanding diamond's role in precision sensing.

Diamond is not limited by its potential — it is limited by our ability to integrate, industrialize, and scale it

One challenge today is compatibility with modern semiconductor manufacturing.

Key enablers include 300 mm process compatibility, low-temperature bonding or deposition, and CMOS-last integration.



Develop

- Leverage material properties
- Advance new products
- Create disruptive technologies



Integrate

- Devices
- Packages
- Systems



Industrialize

- Repeatable manufacturing
- Consistent quality
- Qualified supply chains



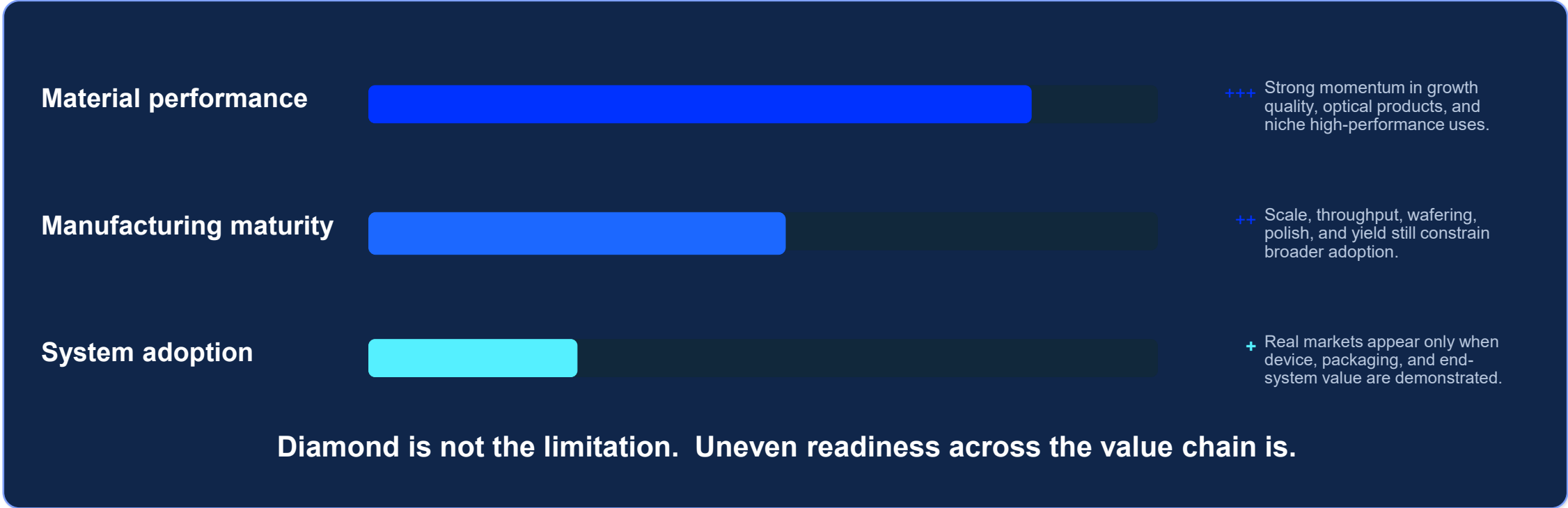
Scale

- High volume production
- Improving yield
- Lowering costs
- Larger sizes/diameter

CURRENT REALITY

Progress is real — but broad adoption is still bottlenecked

Performance, manufacturing readiness, and market pull are not advancing together.



OEMs need credible stepping stones, not a leap of faith

Incremental advances close the gap between current diamond capabilities and OEM application requirements.

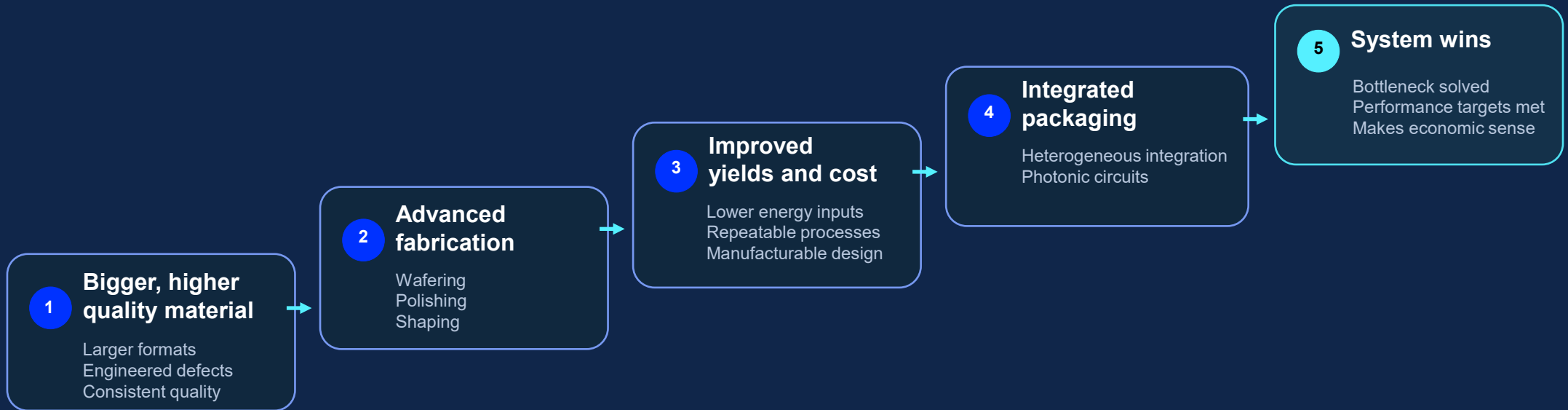


What the next decade must deliver

The path forward is a continual sequence of industrial milestones

Reaching scale will likely require fundamentally new manufacturing approaches

The next breakthroughs may still be hard to predict. The next industrial tasks are not.



Materials alone do not create markets

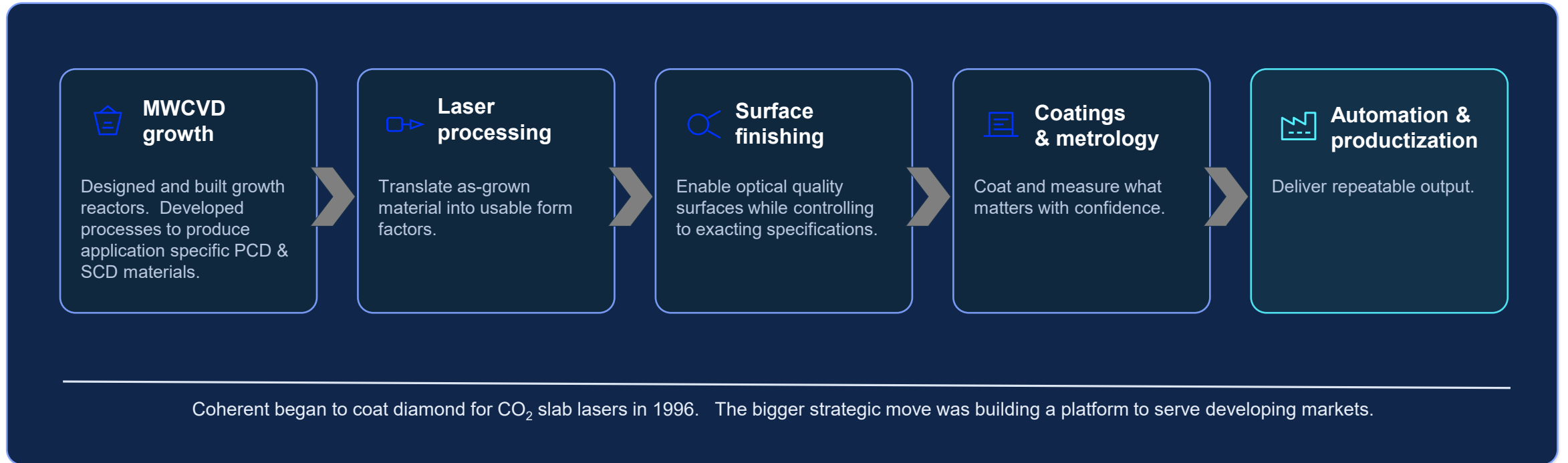
Diamond markets emerge only when every stage of the chain is strong



A break anywhere in this chain can keep diamond technically impressive and commercially small.

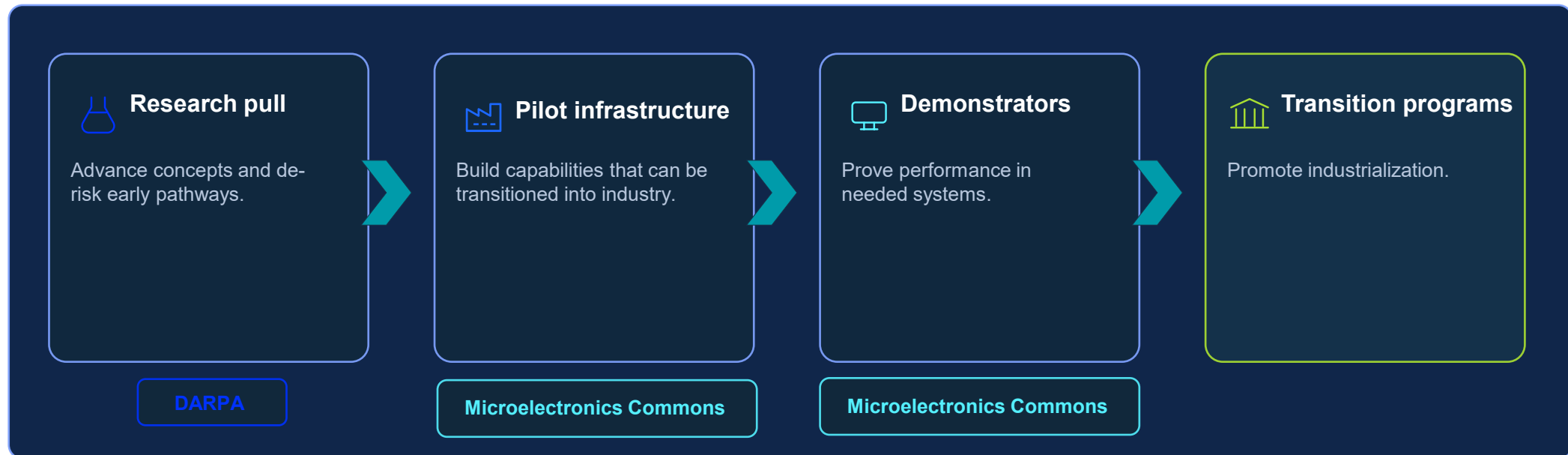
Coherent is building a platform, not just a material offering

That platform spans growth, fabrication, polishing, coatings, and optical metrology - built on decades of process know-how.



Government investment moves the ecosystem forward

The right programs accelerate transition, demand measurable progress, and help bridge the gap.
Visible progress earns continued support.



This site has a history of turning technical innovation into industrial reality

Diamond is the next chapter in that story.



CLOSING

Today, we're positioning diamond for its next 100 years

Advancing the industry requires steady progress in diamond technology and systems integration.

Prove. Integrate. Scale.

That is how diamond moves from remarkable capability to foundational technology.

THANK YOU!

COHERENT CAPABILITIES (REDACTED)

Diamond Background

May 13th, 2026

CVD DIAMOND AT COHERENT

- **Polycrystal diamond sales since 2010**
 - CVD growth technology developed in-house
- **Single Crystal capability added in 2024**
 - IP Licensing Agreement / Tech Transfer with Element Six
- **All processing in Saxonburg, PA**
 - Growth (Poly and Single Crystal)
 - Fabrication (Laser Cutting, Polishing, Marking)
 - Coatings, QA, Metrology



COHERENT DIAMOND PRODUCTS

	Grade	Applications
Polycrystal	Optical	High power CO ₂ laser windows, EUV
	Thermal (T-1500, T-2200)	Heat spreaders for electronics and lasers
	Detector	High-energy physics research
	Microwave	Fusion research, Directed energy
	Composites (CVD/Thermadite)	Cold plates, High Energy Laser Mirrors
Single Crystal	Optical	Hyperspectral
	Thermal	Heat spreaders, direct bondable
	Electronic + Boron Epi	Substrates, Power and RF devices
	Quantum (NV ⁻ diamond)	Sensing, Networks, Computing

Polycrystal sizes to:

- 150mm+ diameter
- ~2.5mm thick

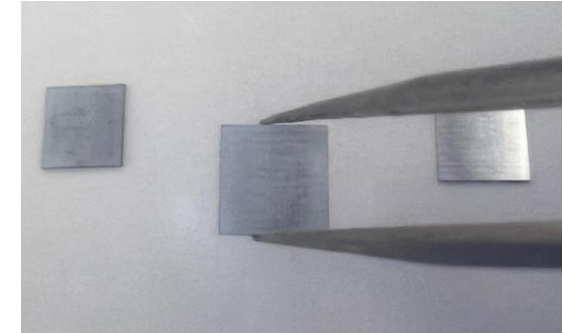
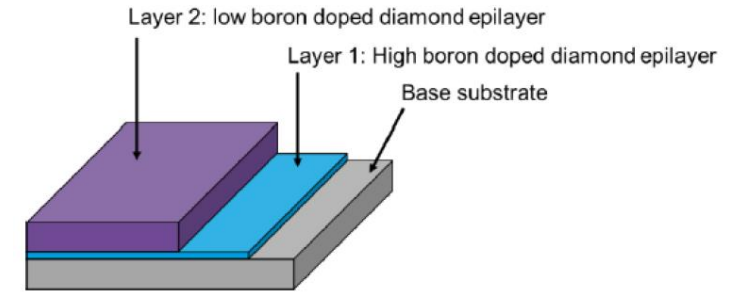
GOVERNMENT PROGRAMS

■ Microelectronics Commons

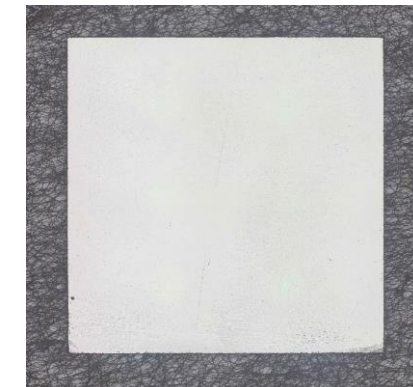
- Develop capability to produce **boron doped diamond epitaxy**
- Deliver materials to GE Research
- Submitted proposals for additional funding
 - Thermal Management
 - Quantum

■ DARPA Ultra-Wide Bandgap Semiconductors (UWBGS)

- Collaboration with The Applied Research Laboratory at Penn State, a UARC facility
- Year 2 goal of delivering high quality 50mm SCD wafers, with optional year delivery of 100mm SCD wafers
- Large-area mosaic single crystal diamond via innovative seed cloning enabled by water-jet laser technology



Conventional Water-Jet



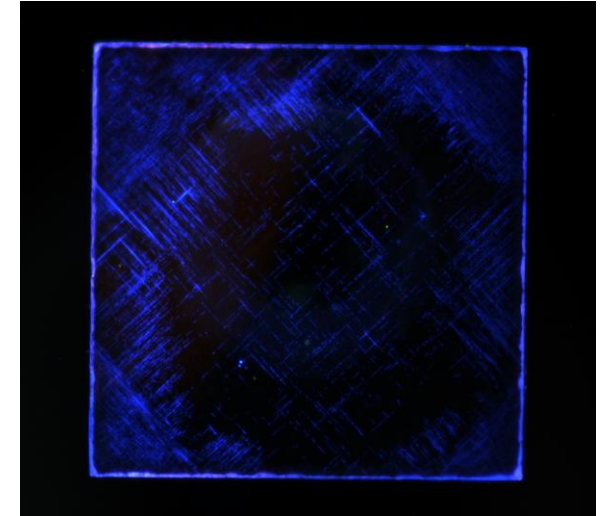
COHERENT CAPABILITIES

Electronic Diamond

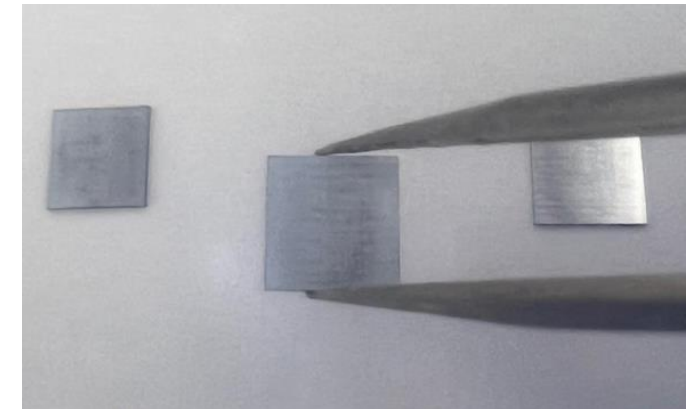
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SCD DIAMOND GROWTH FOR ELECTRONICS APPLICATIONS

- Coherent is expanding its offering of materials for diamond electronics
 - Bulk and epitaxial **undoped** diamond up to 7x7mm²
 - Epitaxial **boron doped** diamond growth (1E16-1E20 atoms/cm⁻³)
- **Dedicated reactor for boron doped diamond**
 - Coherent's first boron-doped SCD grown on-site in October 2025



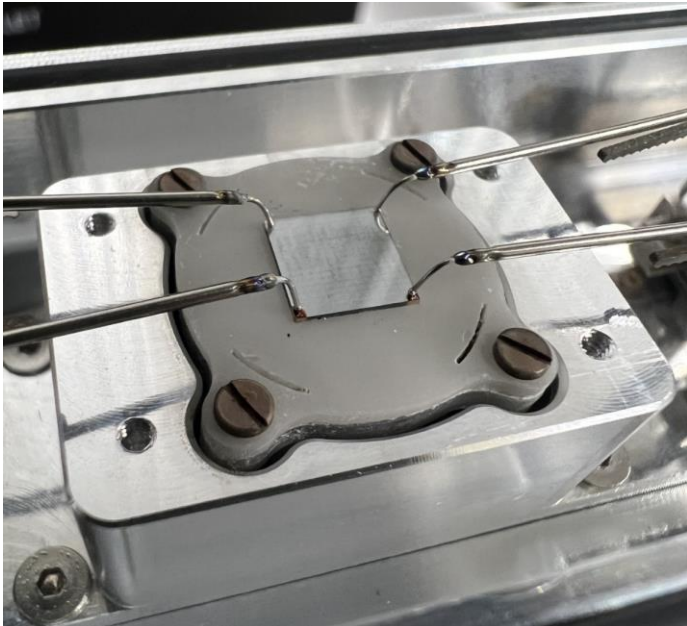
Electronic grade (undoped) SCD



Coherent-grown p-type SCD

ELECTRONIC DIAMOND MATERIALS CHARACTERIZATION CAPABILITIES

- **Hall Effect Measurement System**
 - LakeShore M91 FastHall Controller
 - Temperature control from RT to 1000°C under vacuum
 - Contact metal deposition capabilities in house
- **De-Beers DiamondView Fluorescence Imager**
 - Detect ~ppt [Ns⁰]
- **Panalytical Empyrean X-ray diffractometer**
 - Degree of offcut has an impact on boron incorporation
- **Optical microscope, SEM, AFM and Interferometers**
 - Surface morphology



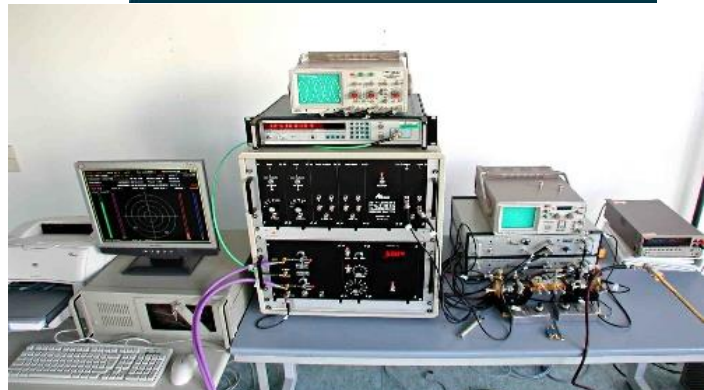
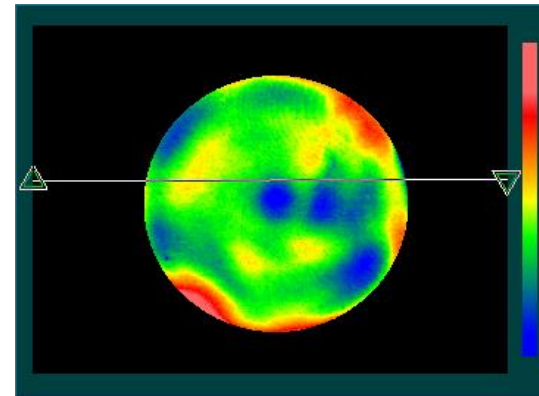
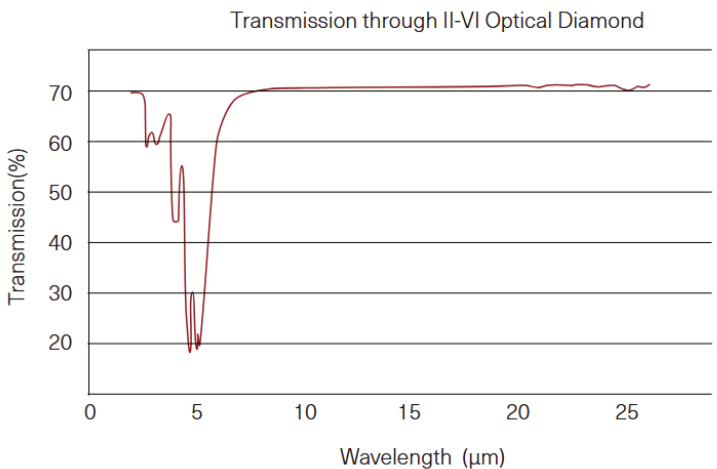
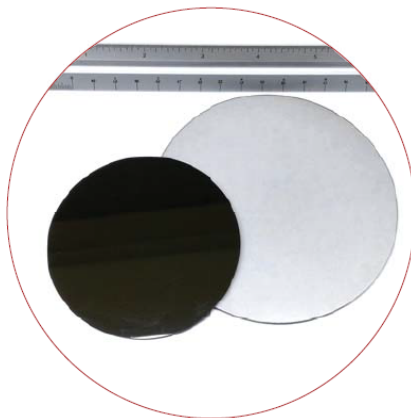
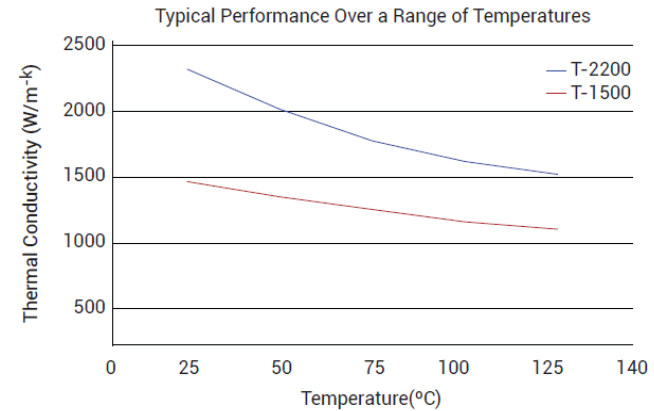
COHERENT CAPABILITIES

Polycrystalline & Quantum Diamond

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POLYCRYSTALLINE DIAMOND

- **QA + Metrology**
 - Laser Flash Analysis (Thermal Diffusivity)
 - UV-Vis/FTIR/10.6 μm Absorption
 - Microwave Loss Tangent
 - Zygo Interferometers

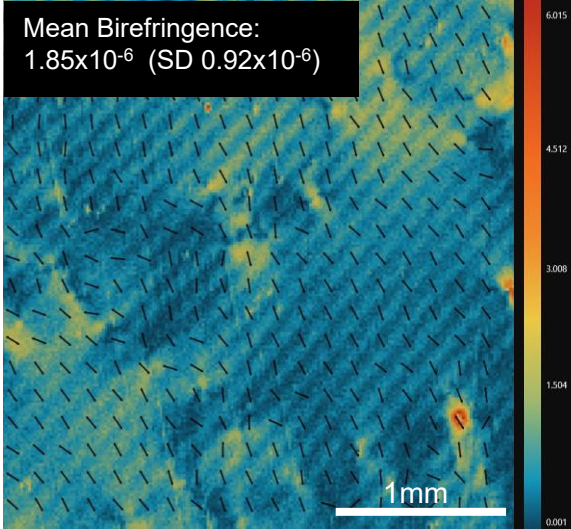


SCD-Q & SCD-Q+

- **SCD-Q – Coherent’s first quantum grade of diamond**
 - Uniform NV distribution, ultra-low strain
 - Optimized for long room temperature T_2 – best suited for AC measurements
- **SCD-Q+ – higher [NV] quantum grade**
 - Same ultra-low strain
 - Higher [NV] while sacrificing minimal T_2^* – best suited for DC measurements



Properties	SCD-Q	SCD-Q+
Typical $[N_s^0]$ (before irradiation)	800 ppb	14 ppm
Typical [NV]	300 ppb	4.5 ppm
Hahn Echo T_2	200 μ s	10 μ s
Ramsey T_2^*	1 μ s	0.5 μ s
Birefringence	$<10^{-5}$	$<10^{-5}$



Retardance measured with 633 nm light source, scale in nm.
Arrows denote Azimuth direction

COHERENT CAPABILITIES

Saxonburg Diamond Fabrication

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COHERENT – SAXONBURG LASER OVERVIEW

- Laser cutting and machining centers
 - Micromachining, Cutting, Scribing, and Laser Marking
 - Many systems: multiple wavelengths, multiple pulse durations and rep rates



- Expertise processing many different material types:

Single crystal diamond	Lithium triborate	Zinc sulfide	...and many others!
Polycrystalline diamond	Gallium oxide	Zinc selenide	
Single crystal SiC	Metal matrix composites	Germanium	
Polycrystalline SiC	Silicon	Graphite	
SiC composites	Polycrystalline silicon	Titanium	
Glass	Metals	Gallium Nitride	

LASER MACHINING CAPABILITIES

- 3D Surfaces using gaussian and flat-top optics
- Many materials: Diamond, SiC, SiSiC, Thermadite,...
- Products for advanced semiconductor packaging processes
- Applications include structures for Liquid and Air Coolers

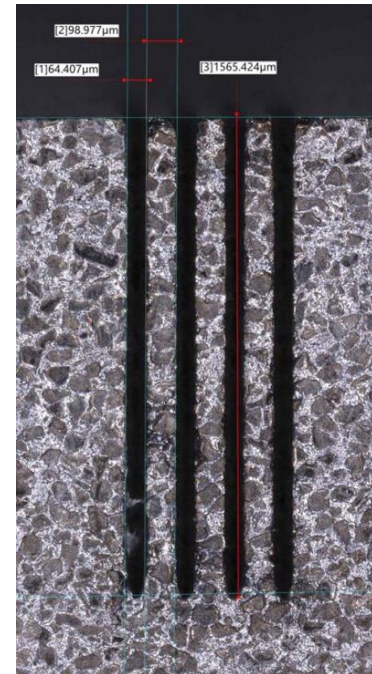
4H SiC



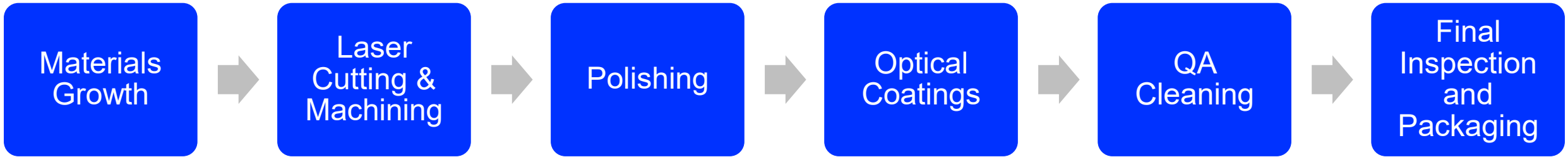
Diamond



Thermadite



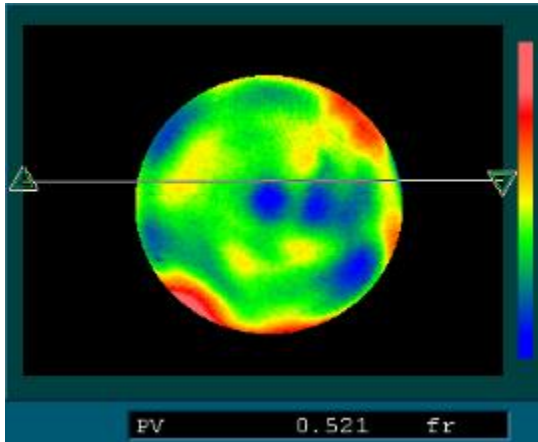
MATERIALS MANUFACTURING PROCESSES AND CAPABILITIES



Laser Cutting,
Machining, and
Marking



Advanced materials
transformation
capabilities



Extreme Flatness and
low Roughness across
large areas



Advanced Optical
Measurement
Capabilities

COHERENT